(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
27 September 2007 (27.09.2007)

PCT

(10) International Publication Number
WO 2007/109486 A3

(51) International Patent Classification:
H01L 23/31 (2006.01) *H01L 21/56* (2006.01)

(21) International Application Number:
PCT/US2007/064028

(22) International Filing Date: 15 March 2007 (15.03.2007)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
11/384,734 20 March 2006 (20.03.2006) US

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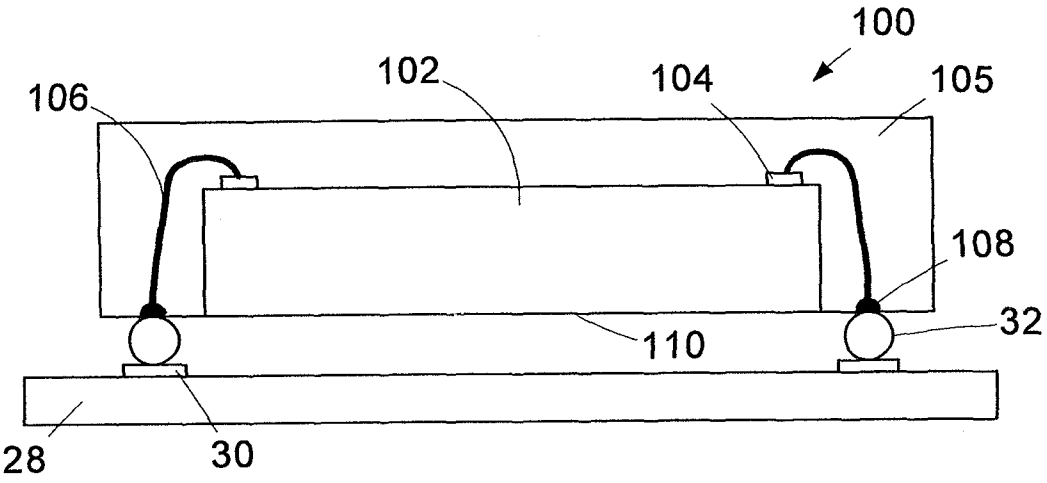
(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*
— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

(88) Date of publication of the international search report:
28 February 2008

(54) Title: CARRIERLESS CHIP PACKAGE FOR INTEGRATED CIRCUIT DEVICES, AND METHODS OF MAKING SAME



(57) Abstract: Disclosed is a carrierless chip package for integrated circuit devices, and various methods of make same. In one illustrative embodiment, the device includes an integrated circuit chip (102) comprising an exposed backside surface (110) defining a plane, a plurality of wire bonds (106) that are conductively coupled to the integrated circuit chip (102), each of the plurality of wire bonds (106) being conductively coupled to a conductive exposed portion (108), a portion of the conductive exposed portion (108) being positioned in the plane defined by the backside surface (110), and an encapsulant material (105) positioned adjacent the integrated circuit chip (102) and the plurality of wire bonds (106).

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